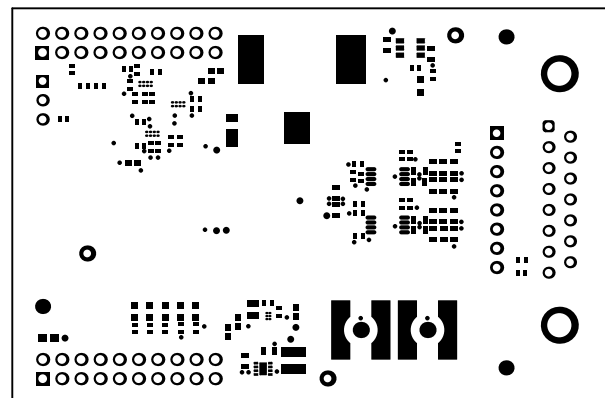
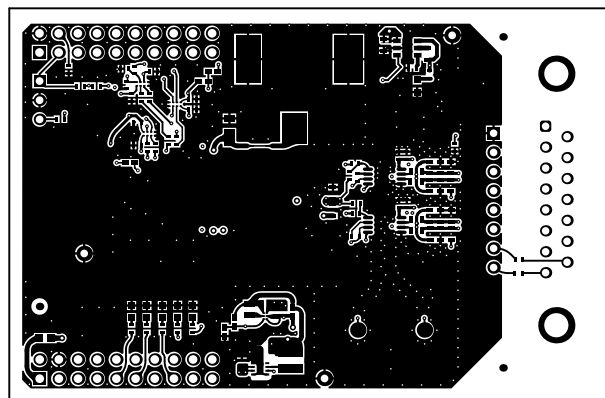


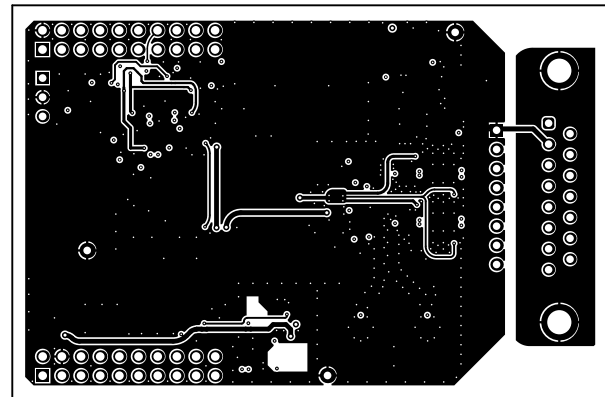
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Top Overlay	TID #: 01401		
PLOT NAME = Top Overlay	GENERATED : 8/17/2017 1:36:52 PM	TEXAS INSTRUMENTS	



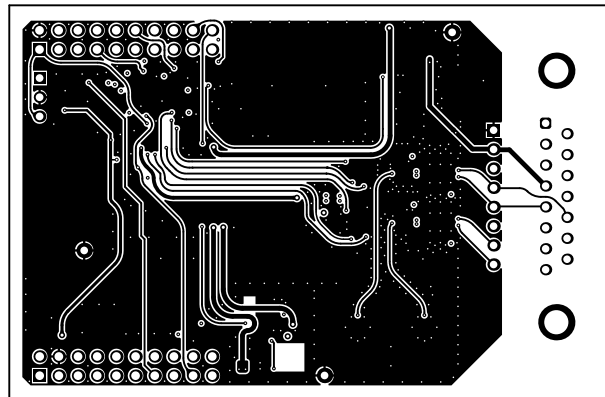
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Top Solder	TID #: 01401		
PLOT NAME = Top Solder Mask	GENERATED : 8/17/2017 1:36:52 PM	TEXAS INSTRUMENTS	



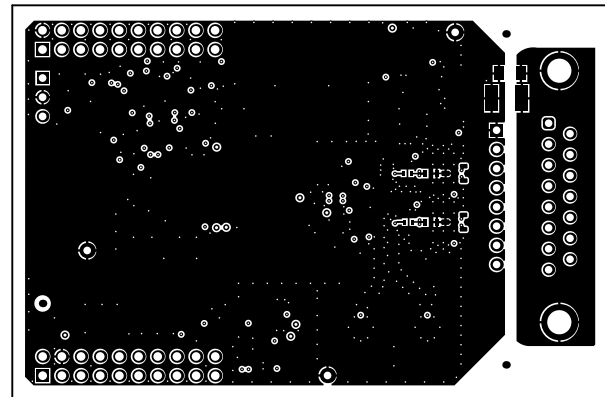
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Top Layer	TID #: 01401		
PLOT NAME = Top Layer	GENERATED : 8/17/2017 1:36:52 PM	TEXAS INSTRUMENTS	



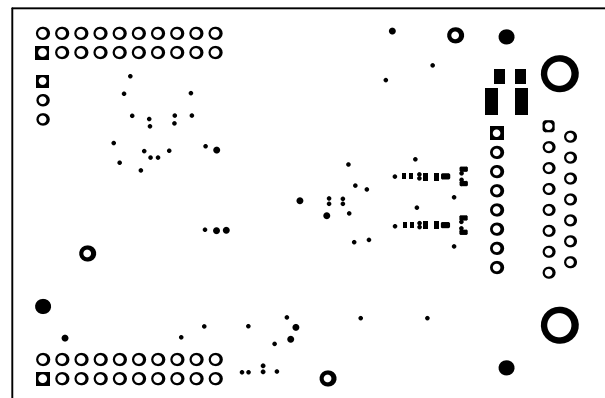
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Signal Layer 1	TID #: 01401		
PLOT NAME = Signal Layer 1	GENERATED : 8/17/2017 1:36:53 PM	TEXAS INSTRUMENTS	



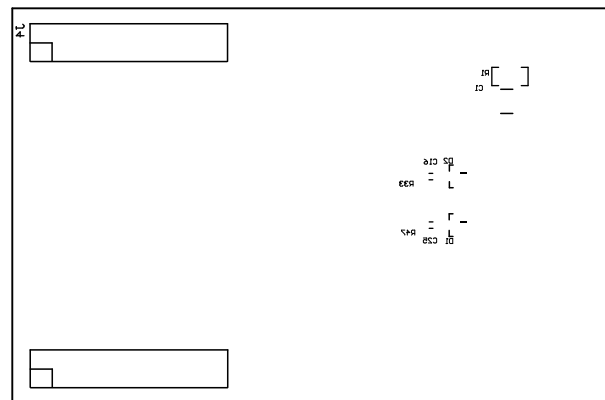
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Signal Layer 2	TID #: 01401		
PLOT NAME = Signal Layer 2	GENERATED : 8/17/2017 1:36:53 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Bottom Layer	TID #: 01401		
PLOT NAME = Bottom Layer	GENERATED : 8/17/2017 1:36:53 PM	TEXAS INSTRUMENTS	

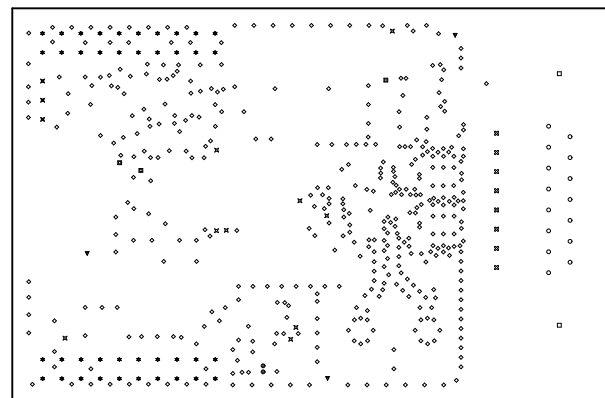


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Bottom Solder	TID #: 01401		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/17/2017 1:36:53 PM	TEXAS INSTRUMENTS	

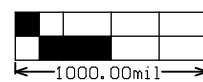
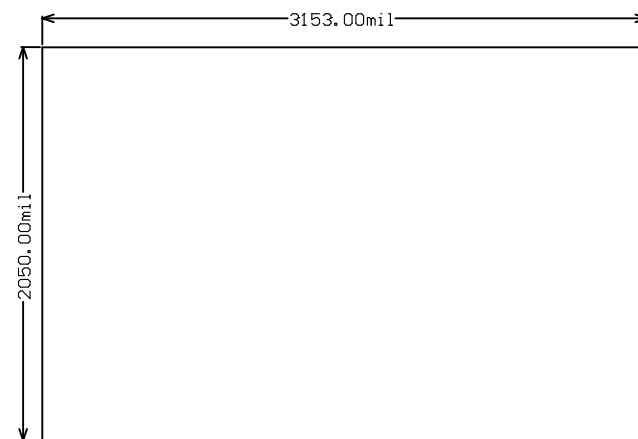


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Bottom Overlay	TID #: 01401		
PLOT NAME = Bottom Overlay	GENERATED : 8/17/2017 1:36:53 PM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
●	2	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
◇	422	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
■	3	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	9	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
○	15	33.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+/-7.87mil
⊞	8	33.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
▼	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	3	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
✱	40	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
□	2	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	+/-11.81mil
	507 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = Drill Drawing	TID #: 01401		
PLOT NAME = Drill Drawing	GENERATED : 8/17/2017	1:36:53 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01401	REV: E2	SUN REV: 1533 [Locally Modified]
LAYER NAME = M2 Board Dimensions	TID #: 01401		
PLOT NAME = Board Dimensions	GENERATED : 8/17/2017 1:36:58 PM	TEXAS INSTRUMENTS	

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